



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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1-15-03
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TECHNOLOGY CENTER 2800

Inventors: Allen K. Lam, Richard K. Williams, Alex K. Choi
Assignee: Advanced Analogic Technologies, Inc. *fee OK*
Title: Symmetrical Package For Semiconductor Die
Serial No.: 10/066,023 Filing Date: 01/30/02
Examiner: Alexander O. Williams Group Art Unit: 2826
Docket No.: AAT009-2D US Confirmation No.: 4878

Santa Clara, California
December 19, 2002

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

This Response to Office Action is responsive to the August 9, 2002 Office Action, which has a statutorily shortened period for response that ended November 9, 2002. Enclosed with this Response is a petition for an extension of time allowing Applicants until January 9, 2003 in which to respond to the Office Action.

Please enter the following amendments before taking action on the merits of the above-referenced application.

In the Title

(changed in PALM)

01/21/2003 LSPRUELL 00000001 502263 10066023

1 FC:2201 34.00 CH
2 FC:2202 63.00 CH
--PACKAGE FOR SEMICONDUCTOR DIE CONTAINING HEAT SINK
AND LEAD EXTENDING FROM OPPOSITE SIDES OF DIE--

In the Specification

The paragraph beginning at page 1, line 6, is amended to read as follows:

This application is a divisional of Application No. 09/898,212, filed July 2, 2001, now U.S. Patent No. 6,452,802, issued September 17, 2002, which is a continuation of Application No. 09/322,124, filed May 27, 1999, now U.S. Patent No. 6,256,200, issued July 3, 2001, and

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